

HZC Series

Silicon Epitaxial Planar Zener Diode for Surge Absorb

REJ03G1204-0200
(Previous: ADE-208-1436A)
Rev.2.00
Jul 04, 2005

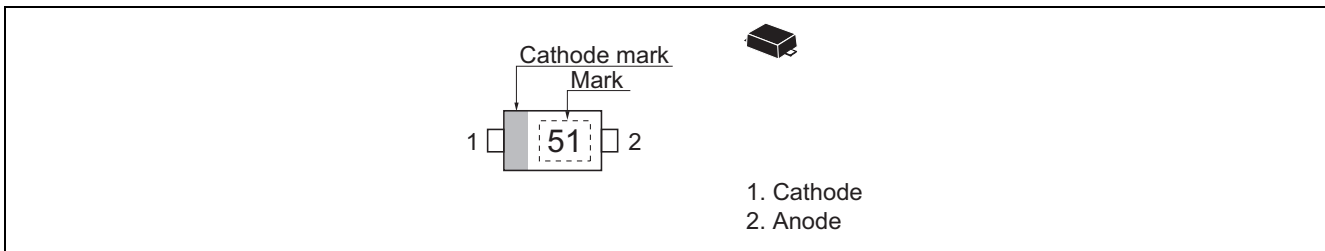
Features

- These diodes are delivered taped.
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HZC Series	Let to Mark Code	UFP	PWSF0002ZA-A (UFP)

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

tem	Symbol	Value	Unit
Power dissipation	Pd *	150	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: See Fig2.

Electrical Characteristics

(Ta = 25°C)

Type No.	Zener Voltage		Reverse Current		Dynamic Resistance		ESD-Capability *2	
	V _Z (V) *1		I _R (μA)	Test Condition	r _d (Ω)	Test Condition	— (kV) *2	
	Min	Max	Max	V _R (V)	Max	I _Z (mA)	Min	
H2C2.0	1.90	2.20	5	120.0	0.5	100	5	30
H2C2.2	2.10	2.40	5	120.0	0.7	100	5	30
H2C2.4	2.30	2.60	5	120.0	1.0	100	5	30
H2C2.7	2.50	2.90	5	120.0	1.0	110	5	30
H2C3.0	2.80	3.20	5	50.0	1.0	120	5	30
H2C3.3	3.10	3.50	5	20.0	1.0	130	5	30
H2C3.6	3.40	3.80	5	10.0	1.0	130	5	30
H2C3.9	3.70	4.10	5	10.0	1.0	130	5	30
H2C4.3	4.01	4.48	5	10.0	1.0	130	5	30
H2C4.7	4.42	4.90	5	10.0	1.0	130	5	30
H2C5.1	4.84	5.37	5	5.0	1.5	130	5	30
H2C5.6	5.31	5.92	5	5.0	2.5	80	5	30
H2C6.2	5.86	6.53	5	2.0	3.0	50	5	30
H2C6.8	6.47	7.14	5	1.0	3.5	30	5	30
H2C7.5	7.06	7.84	5	1.0	4.0	30	5	30
H2C8.2	7.76	8.64	5	0.5	5.0	30	5	30
H2C9.1	8.56	9.55	5	0.5	6.0	30	5	30
H2C10	9.45	10.55	5	0.5	7.0	30	5	30
H2C11	10.44	11.56	5	0.5	8.0	30	5	30
H2C12	11.42	12.60	5	0.5	9.0	35	5	30
H2C13	12.47	13.96	5	0.5	10.0	35	5	30
H2C15	13.84	15.52	5	0.5	11.0	40	5	30
H2C16	15.37	17.09	5	0.5	12.0	40	5	30
H2C18	16.94	19.03	5	0.5	13.0	45	5	30
H2C20	18.86	21.08	5	0.5	15.0	50	5	30
H2C22	20.88	23.17	5	0.5	17.0	55	5	30
H2C24	22.93	25.57	5	0.5	19.0	60	5	30
H2C27	25.10	28.90	2	0.5	21.0	70	2	30
H2C30	28.00	32.00	2	0.5	23.0	80	2	30
H2C33	31.00	35.00	2	0.5	25.0	80	2	25
H2C36	34.00	38.00	2	0.5	27.0	90	2	20

Notes: 1. Tested with pulse (Pw = 40 ms).

2. C = 150 pF, R = 330 Ω, Both forward and reverse direction 10 pulse
Failure criterion ; According to IR spec

Mark Code

Type No.	Mark No.
HZC2.0	20
HZC2.2	22
HZC2.4	24
HZC2.7	27
HZC3.0	30
HZC3.3	33
HZC3.6	36
HZC3.9	39
HZC4.3	43
HZC4.7	47
HZC5.1	51
HZC5.6	56
HZC6.2	62
HZC6.8	68
HZC7.5	75
HZC8.2	82
HZC9.1	91
HZC10	10 *
HZC11	11 *
HZC12	12 *
HZC13	13 *
HZC15	15 *
HZC16	16 *
HZC18	18 *
HZC20	20 *
HZC22	22 *
HZC24	24 *
HZC27	27 *
HZC30	30 *
HZC33	33 *
HZC36	36 *

Note: HZC10 To HZC36 has ■, on the right of Laser Mark.

Main Characteristic

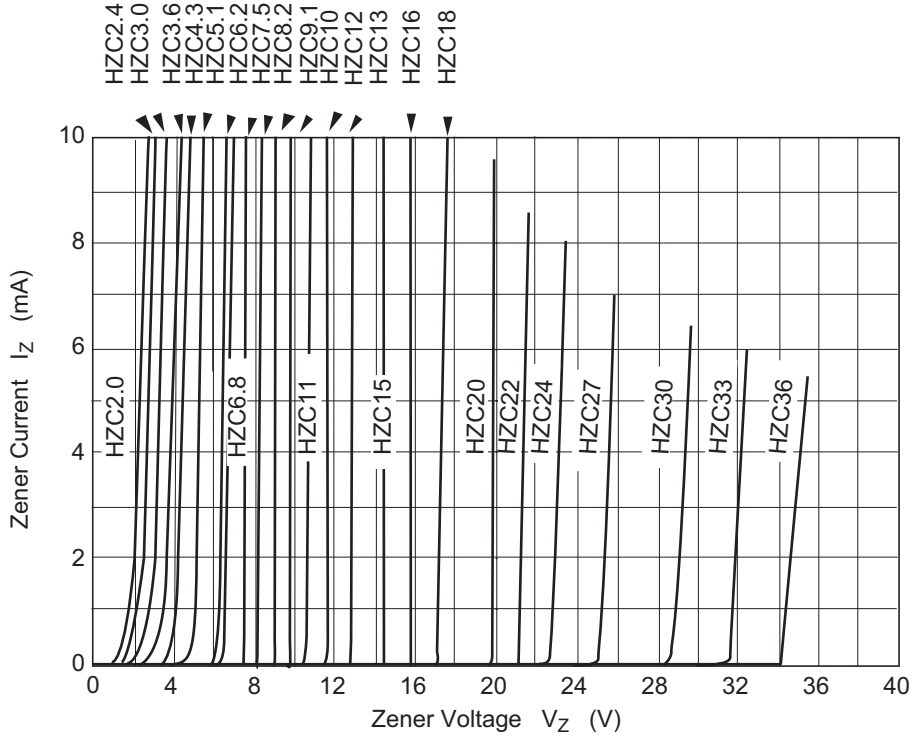


Fig.1 Zener current vs. Zener voltage

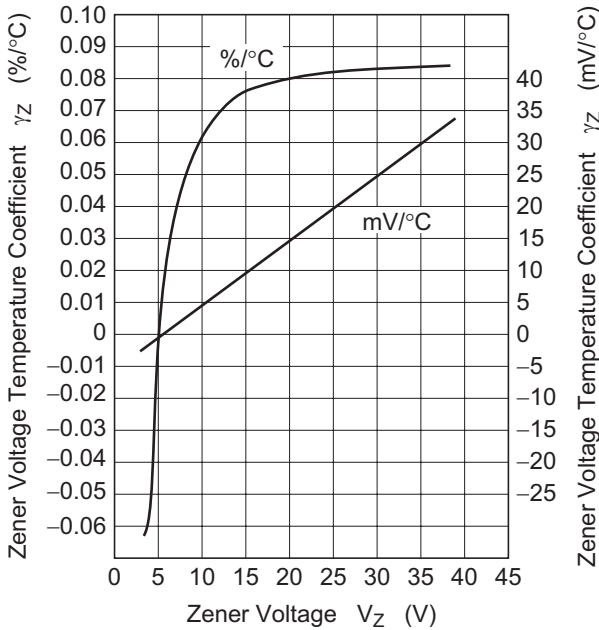


Fig.2 Temperature Coefficient vs. Zener voltage

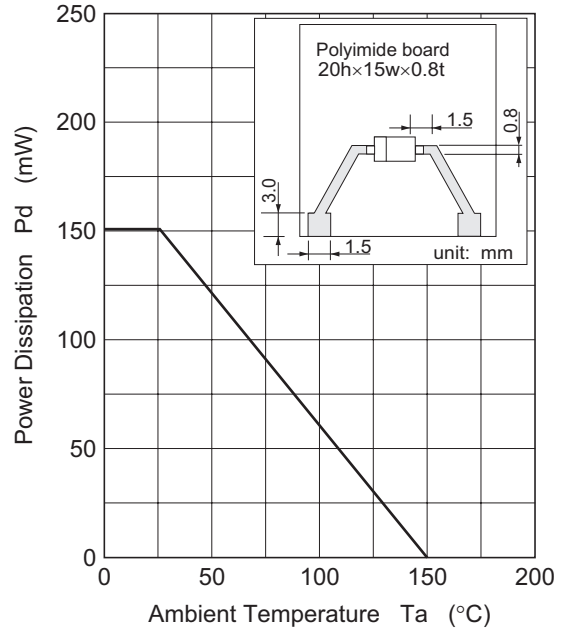
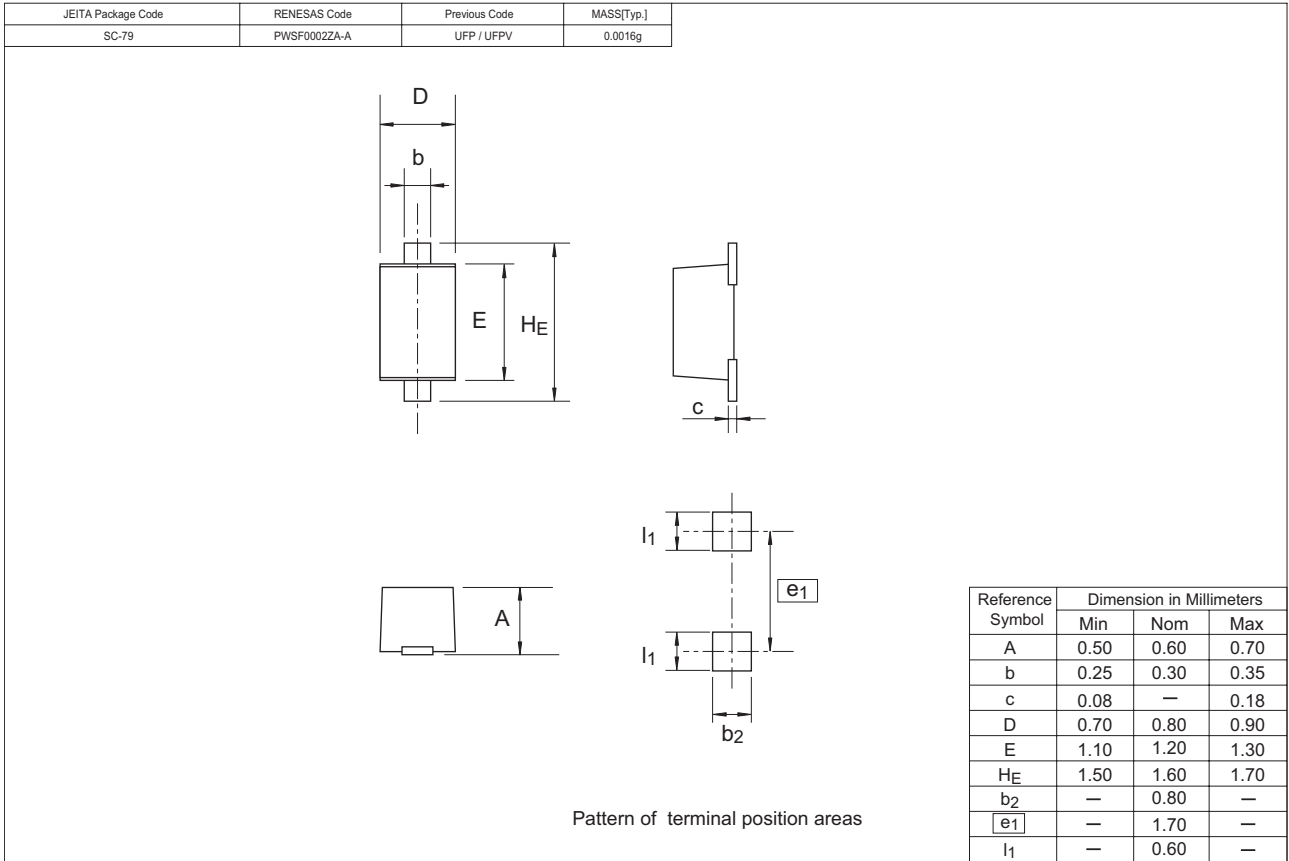


Fig.2 Power Dissipation vs. Ambient Temperature

Package Dimensions



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